

## **APPLICATION NOTE**

# **Construction of the 470 – 860 MHz BLV57 wideband amplifier**

**NCO8201**

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### 1 INTRODUCTION

In the application report NCO8101 two amplifiers for band 4/5 with BLV57 transistors have been described. Reactions on this report proved the necessity to give more information about the construction of these amplifiers. This construction has been based on a heatsink with a printed-circuit board at the upper side and the bias circuits and a forced air-cooling at the lower side.

### 2 PRINTED CIRCUIT BOARD

In the printed-circuit board rectangular holes have been made to mount the BLV57 transistors on the heatsink. For fastening of the printed-circuit board on the heatsink by means of screws, 7 holes of 3.1 mm  $\varnothing$  and for fastening of the hybrid couplers 8 holes of 2.6 mm  $\varnothing$  have been made on the indicated places (see Figs 1 and 2). Hereby has been taken into account the use of Anaren hybrid couplers, type 10264 – 3, suited for the frequency range of 500 – 1000 MHz. Because the 2 bias units have been situated at the lower side of the heatsink, the connections from these units to the circuit take place through the printed-circuit board and the heatsink. For this purpose 9 holes of 2 mm  $\varnothing$  are necessary (4 collectors, 4 bases and 1 ground). To make a good ground contact between the upper and the lower side of the printed-circuit board the following measures have been taken:

- On 8 spots rivets have been used and soldered at both sides to the metallization of the printed-circuit board. The holes of 2 mm  $\varnothing$ , needed for these rivets, have been situated as indicated in Figs 1 and 2.
- Copper straps with a thickness of 0.2 mm have been soldered at all edges of the printed-circuit board.
- A good emitter to ground contact has been achieved by soldering 8 copper straps from the upper to the lower side of the printed-circuit board on the spots of each emitter lead.
- The input connector and the output connector have been screwed to the heatsink but the ground also has been soldered to the printed-circuit board.

### 3 HEATSINK

For the BLV57 amplifiers, described in report NCO8101, a blackened heatsink of Seifert Electronic, type KL-117 with a length of 191 mm has been used (see Fig.3). At the lower side forced air-cooling has been applied with a fan trade mark Etri, type 99 XU 01 - 81 with an air displacement of 16 litres per second). By applying this air-cooling the thermal resistance decreased from 0.5 °C/W to 0.2 °C/W.

### 4 MECHANICAL MACHINING OF THE HEATSINK

The raised edges at the top side of the heatsink have been removed because the printed circuit board has a width of 113 mm (see Fig.3). To fit the heatsink to the printed-circuit board the following machinings have been carried out:

- Rectangular holes of 2.8 mm deep have been mould in the heatsink because the transistor leads have to be soldered on the printed-circuit board. Also it was necessary to make savings of 4 mm wide and 0.6 mm deep at the positions of the straps on the printed-circuit board. The transistors have been fastened with M 2.5 screws in the heatsink (see Fig.4).
- To achieve that the printed-circuit board lays tight to the heatsink also savings have been made in the heatsink on the spots of the 8 rivets through the printed-circuit board.
- For fastening the printed-circuit board on the heatsink on 7 places, holes with M 3 screwthread have been made in the top side of the heatsink, corresponding with indicated holes in the printed-circuit board.
- The two hybrid couplers also have been fastened in the heatsink with screws through the printed-circuit board. Therefore 8 holes have been made with M 2.5 screwthread, corresponding with the printed-circuit board.
- The input and output connectors have been fastened to the heatsink with M 3 screws. The mid contact of each connector makes contact with the printed-circuit board.

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### 5 CONCLUSIONS

With the construction of the BLV57 amplifiers a good thermal resistance ( $0.2\text{ }^{\circ}\text{C/W}$ ) has been achieved by means of a forced air-cooling. Attention has been paid to a good mechanical contact between heatsink and printed circuit board and a good ground contact on the printed-circuit board by means of rivets and straps at the edges and under the emitter leads.

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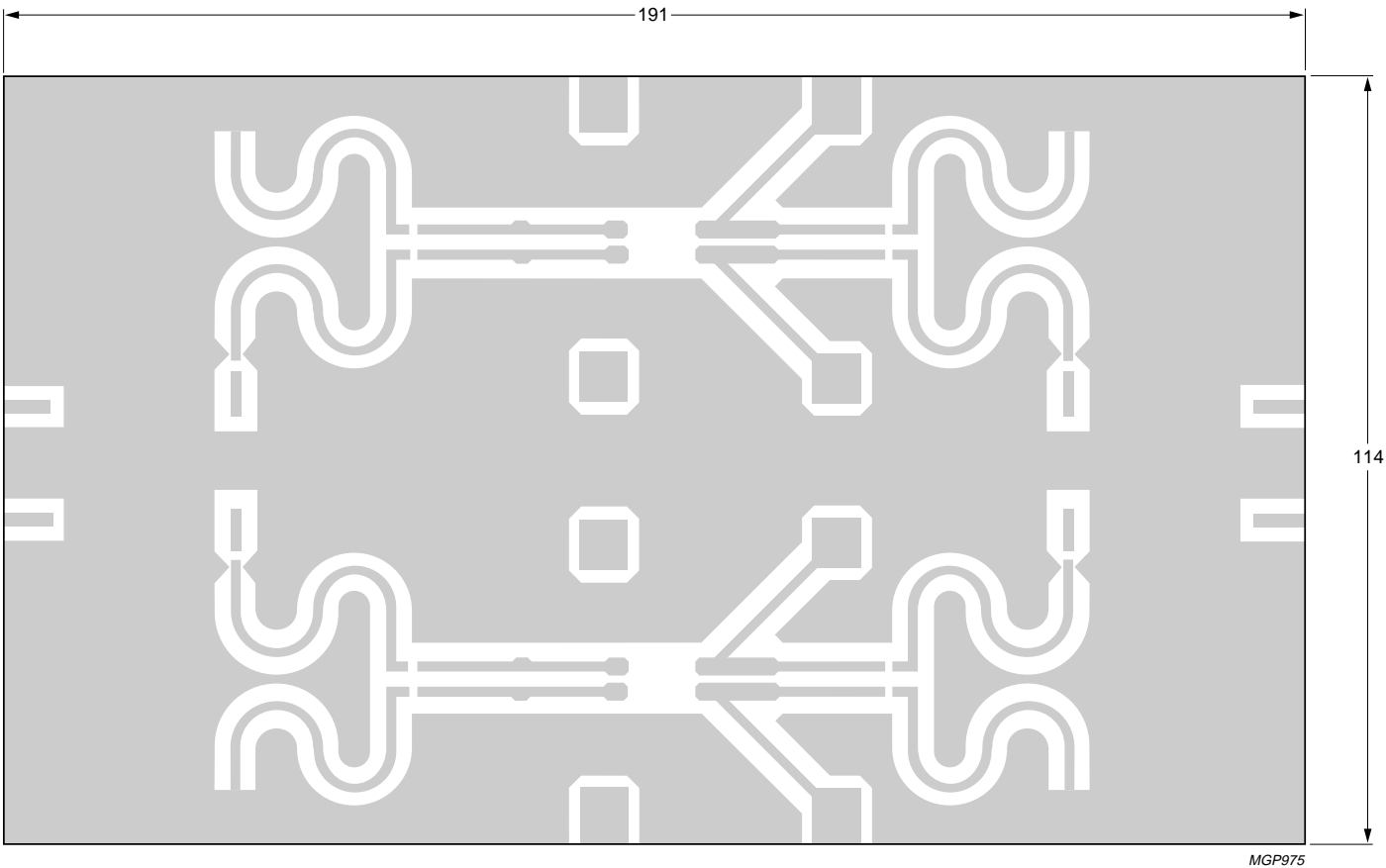


Fig.1 Printed circuit board.

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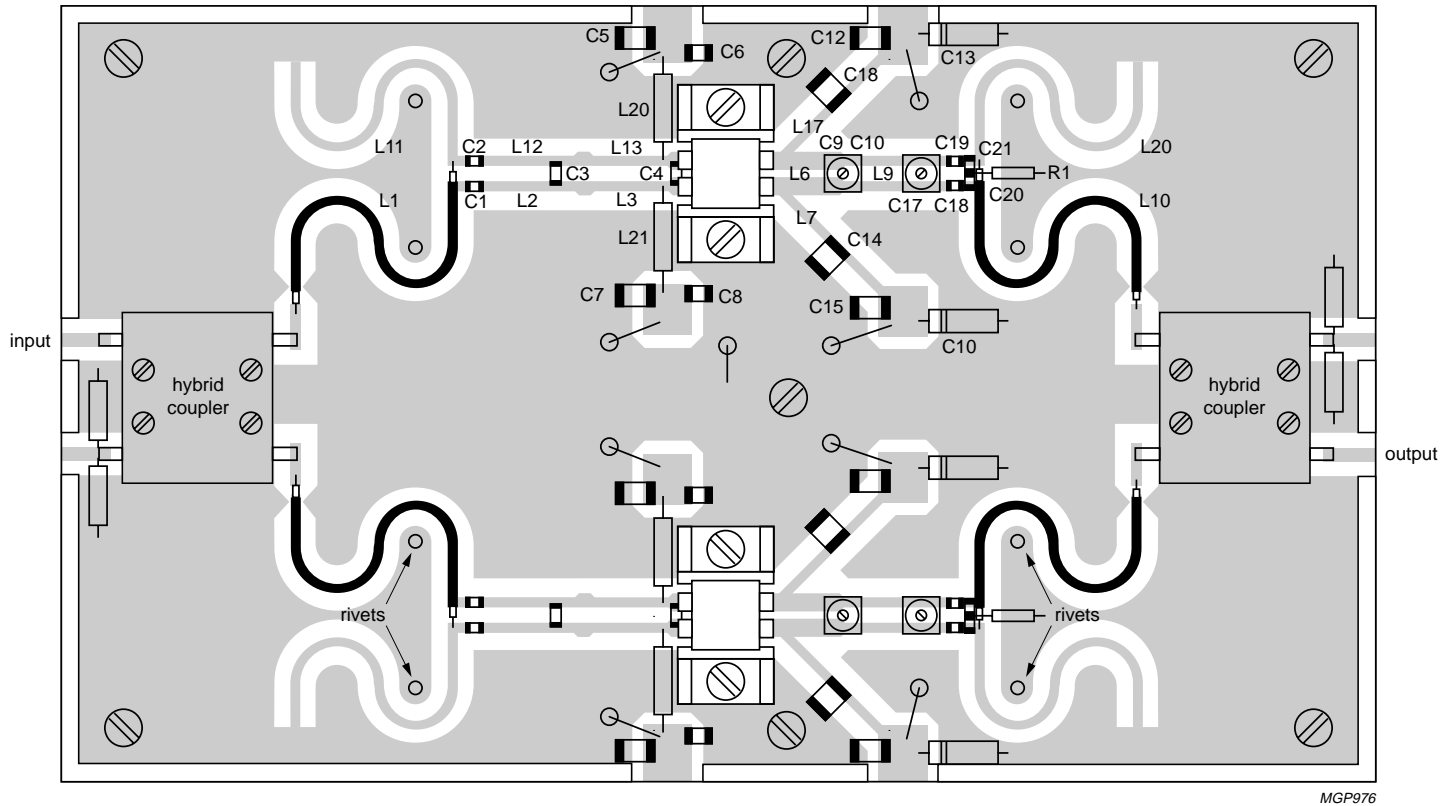


Fig.2 Printed-circuit board.

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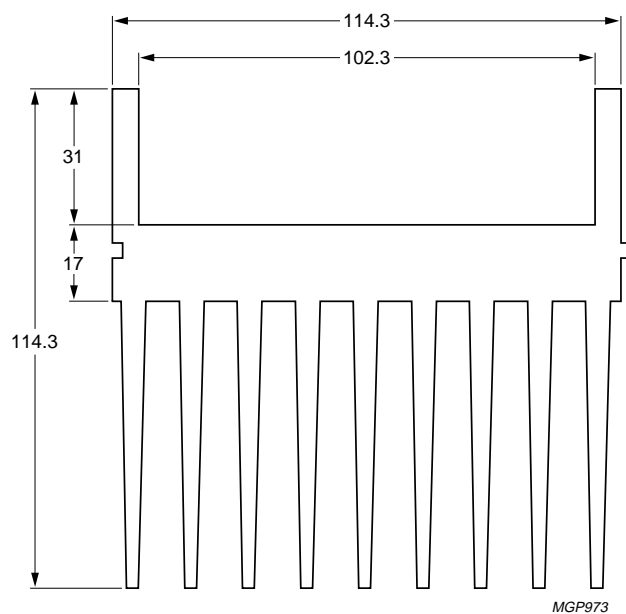


Fig.3 Heatsink.

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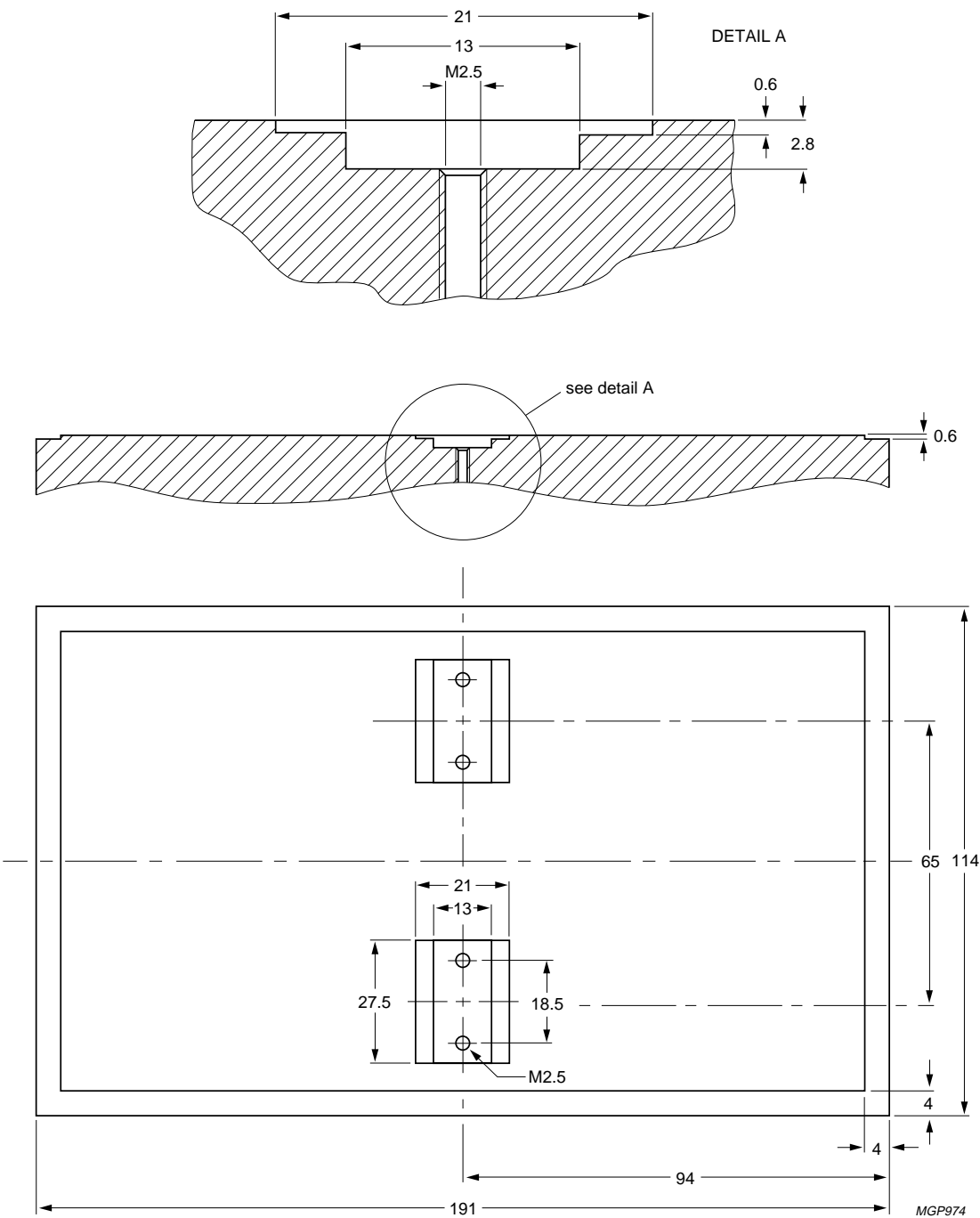


Fig.4 Heatsink savings.



# Philips Semiconductors – a worldwide company

**Argentina:** see South America

**Australia:** 34 Waterloo Road, NORTH RYDE, NSW 2113,  
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

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Fax. +43 160 101 1210

**Belarus:** Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,  
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Tel. +359 2 689 211, Fax. +359 2 689 102

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**Denmark:** Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,  
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Tel. +358 9 615800, Fax. +358 9 61580920

**France:** 51 Rue Carnot, BP317, 92156 SURESNES Cedex,  
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Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

**Greece:** No. 15, 25th March Street, GR 17778 TAVROS/ATHENS,  
Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

**Hungary:** see Austria

**India:** Philips INDIA Ltd, Band Box Building, 2nd floor,  
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,  
Tel. +91 22 493 8541, Fax. +91 22 493 0966

**Indonesia:** see Singapore

**Ireland:** Newstead, Clonskeagh, DUBLIN 14,  
Tel. +353 1 7640 000, Fax. +353 1 7640 200

**Israel:** RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,  
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

**Italy:** PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,  
20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

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**Korea:** Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,  
Tel. +82 2 709 1412, Fax. +82 2 709 1415

**Malaysia:** No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,  
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**Mexico:** 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,  
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**Middle East:** see Italy

**Netherlands:** Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,  
Tel. +31 40 27 82785, Fax. +31 40 27 88399

**New Zealand:** 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,  
Tel. +64 9 849 4160, Fax. +64 9 849 7811

**Norway:** Box 1, Manglerud 0612, OSLO,  
Tel. +47 22 74 8000, Fax. +47 22 74 8341

**Philippines:** Philips Semiconductors Philippines Inc.,  
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,  
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

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Tel. +27 11 470 5911, Fax. +27 11 470 5494

**South America:** Al. Vicente Pinzon, 173, 6th floor,  
04547-130 SÃO PAULO, SP, Brazil,  
Tel. +55 11 821 2333, Fax. +55 11 821 2382

**Spain:** Balmes 22, 08007 BARCELONA,  
Tel. +34 3 301 6312, Fax. +34 3 301 4107

**Sweden:** Kottbygatan 7, Akalla, S-16485 STOCKHOLM,  
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**Switzerland:** Allmendstrasse 140, CH-8027 ZÜRICH,  
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**Taiwan:** Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,  
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**Ukraine:** PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,  
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

**United Kingdom:** Philips Semiconductors Ltd., 276 Bath Road, Hayes,  
MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

**United States:** 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,  
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